

We claim:

1. An electronic component, comprising:

a housing made of a casting or a molding compound;

an integrated circuit having a base area; and

a lead frame having an island with a base area supporting said integrated circuit, a ratio between the base area of said integrated circuit and the base area of said island being from 0.7 to 0.9 for avoiding flexure of said housing;

said integrated circuit and said island embedded in said housing so that a thickness of a housing region above said integrated circuit is substantially equal to a thickness of a housing region below said island.

2. The electronic component according to claim 1, including an adhesive bonding said integrated circuit to said island, and a hollow groove formed on said integrated circuit by an amount of adhesive that has emerged from between said integrated circuit and said island.

3. The electronic component according to claim 1, wherein the base area of said island is a continuous, unpatterned area.

4. The electronic component according to claim 1, wherein said lead frame includes leads that are routed to said island.

5. The electronic component according to claim 1, wherein said lead frame includes leads that are vertically centered within said housing, and said island is vertically lowered with respect to said leads.

6. An electronic component, comprising:

a housing made of casting or molding compound;

an integrated circuit having a base area; and

a lead frame having an island with a base area supporting said integrated circuit, the base area of said island being greater than the base area of said integrated circuit for avoiding flexure of said housing;

said integrated circuit and said island embedded in said housing so that a thickness of a housing region above said integrated circuit is substantially equal to a thickness of a housing region below said island.